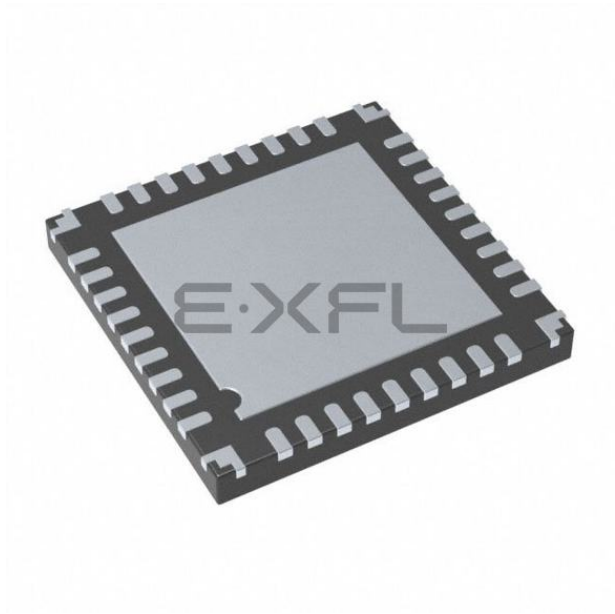

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	36-UFQFN Exposed Pad
Supplier Device Package	36-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev32gm003-e-m5

Table 9-1 provides the Configuration bits which allow users to choose between the various clock modes.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>
Fast RC Oscillator with Divide-by-N (FRCDIVN)(1,2)	Internal	xx	111
Fast RC Oscillator with Divide-by-16 (FRCDIV16)(1)	Internal	xx	110
Low-Power RC Oscillator (LPRC)(1)	Internal	xx	101
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011
Primary Oscillator (EC) with PLL (ECPLL)(1)	Primary	00	011
Primary Oscillator (HS)	Primary	10	010
Primary Oscillator (XT)	Primary	01	010
Primary Oscillator (EC)(1)	Primary	00	010
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)(1)	Internal	xx	001
Fast RC Oscillator (FRC)(1)	Internal	xx	000

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

11.6 High-Voltage Detect (HVD)

dsPIC33EVXXXGM00X/10X devices contain High-Voltage Detection (HVD) which monitors the VCAP voltage. The HVD is used to monitor the VCAP supply voltage to ensure that an external connection does not raise the value above a safe level (~2.4V). If high core voltage is detected, all I/Os are disabled and put in a tri-state condition. The device remains in this I/O tri-state condition as long as the high-voltage condition is present.

11.7 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-10 under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name, from left-to-right. The left most function name takes precedence over any function to its right in the naming convention; for example, AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specifications. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   VOH = 4.4V at IOH = -8 mA and VDD = 5V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current, <12 mA, is technically permitted. For more information, refer to the VOH/IOH specifications in **Section 30.0 “Electrical Characteristics”**.

REGISTER 17-7: PWMCONx: PWMx CONTROL REGISTER (CONTINUED)

bit 7-6 **DTC<1:0>:** Dead-Time Control bits
11 = Dead-Time Compensation mode
10 = Dead-time function is disabled
01 = Negative dead time is actively applied for Complementary Output mode
00 = Positive dead time is actively applied for all Output modes

bit 5 **DTCP:** Dead-Time Compensation Polarity bit(3)
When Set to '1':
If DTCMPx = 0, PWMxL is shortened and PWMxH is lengthened.
If DTCMPx = 1, PWMxH is shortened and PWMxL is lengthened.
When Set to '0':
If DTCMPx = 0, PWMxH is shortened and PWMxL is lengthened.
If DTCMPx = 1, PWMxL is shortened and PWMxH is lengthened.

bit 4-3 **Unimplemented:** Read as '0'

bit 2 **CAM:** Center-Aligned Mode Enable bit(2,4)
1 = Center-Aligned mode is enabled
0 = Edge-Aligned mode is enabled

bit 1 **XPRES:** External PWMx Reset Control bit(5)
1 = Current-limit source resets the time base for this PWM generator if it is in Independent Time Base mode
0 = External pins do not affect PWMx time base

bit 0 **IUE:** Immediate Update Enable bit(2)
1 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are immediate
0 = Updates to the active MDC/PDCx/DTRx/ALTDTRx/PHASEx registers are synchronized to the PWMx period boundary

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; else, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER (CONTINUED)

bit 1 **SPITBF:** SPIx Transmit Buffer Full Status bit

1 = Transmit has not yet started, the SPIxTXB bit is full
0 = Transmit has started, the SPIxTXB bit is empty

Standard Buffer mode:
Automatically set in hardware when the core writes to the SPIxBUF location, loading SPIxTXB. Automatically cleared in hardware when the SPIx module transfers data from SPIxTXB to SPIxSR.

Enhanced Buffer mode:
Automatically set in the hardware when the CPU writes to the SPIxBUF location, loading the last available buffer location. Automatically cleared in hardware when a buffer location is available for a CPU write operation.

bit 0 **SPIRBF:** SPIx Receive Buffer Full Status bit

1 = Receive is complete, the SPIxRXB bit is full
0 = Receive is incomplete, the SPIxRXB bit is empty

Standard Buffer mode:
Automatically set in the hardware when SPIx transfers data from SPIxSR to SPIxRXB. Automatically cleared in hardware when the core reads the SPIxBUF location, reading SPIxRXB.

Enhanced Buffer mode:
Automatically set in hardware when SPIx transfers data from SPIxSR to the buffer, filling the last unread buffer location. Automatically cleared in hardware when a buffer location is available for a transfer from SPIxSR.

FIGURE 20-1: SENTx MODULE BLOCK DIAGRAM

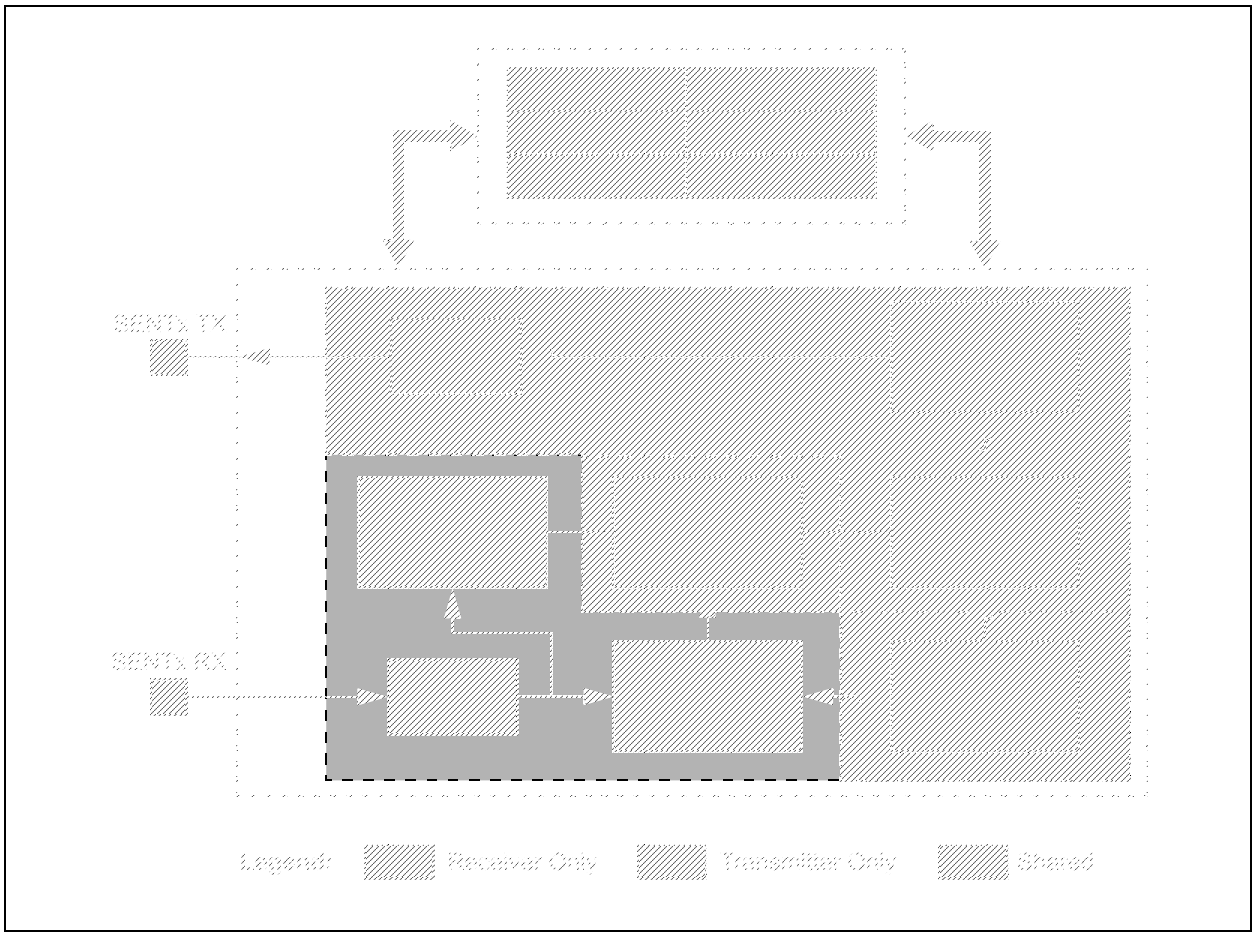
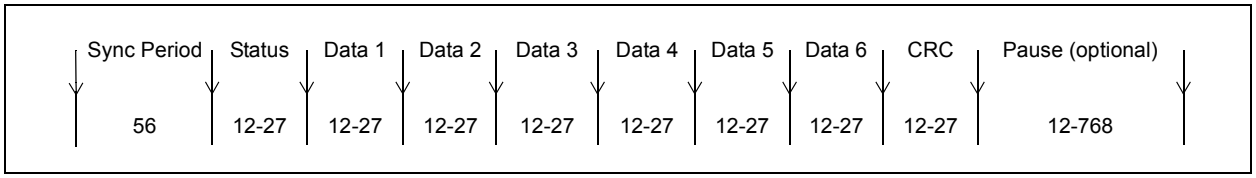


FIGURE 20-2: SENTx PROTOCOL DATA FRAMES



REGISTER 20-2: SENTxSTAT: SENTx STATUS REGISTER (CONTINUED)

bit 0 **SYNCTXEN:** SENTx Synchronization Period Status/Transmit Enable bit(1)

Module in Receive Mode (RCVEN = 1):

1 = A valid synchronization period was detected; the module is receiving nibble data

0 = No synchronization period has been detected; the module is not receiving nibble data

Module in Asynchronous Transmit Mode (RCVEN = 0, TXM = 0):

The bit always reads as '1' when the module is enabled, indicating the module transmits SENTx data frames continuously. The bit reads '0' when the module is disabled.

Module in Synchronous Transmit Mode (RCVEN = 0, TXM = 1):

1 = The module is transmitting a SENTx data frame

0 = The module is not transmitting a data frame, user software may set SYNCTXEN to start another data frame transmission

Note 1: In Receive mode (RCVEN = 1), the SYNCTXEN bit is read-only.

21.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Universal Asynchronous Receiver Transmitter (UART)"** (DS70000582) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EVXXXGM00X/10X family of devices contains two UART modules.

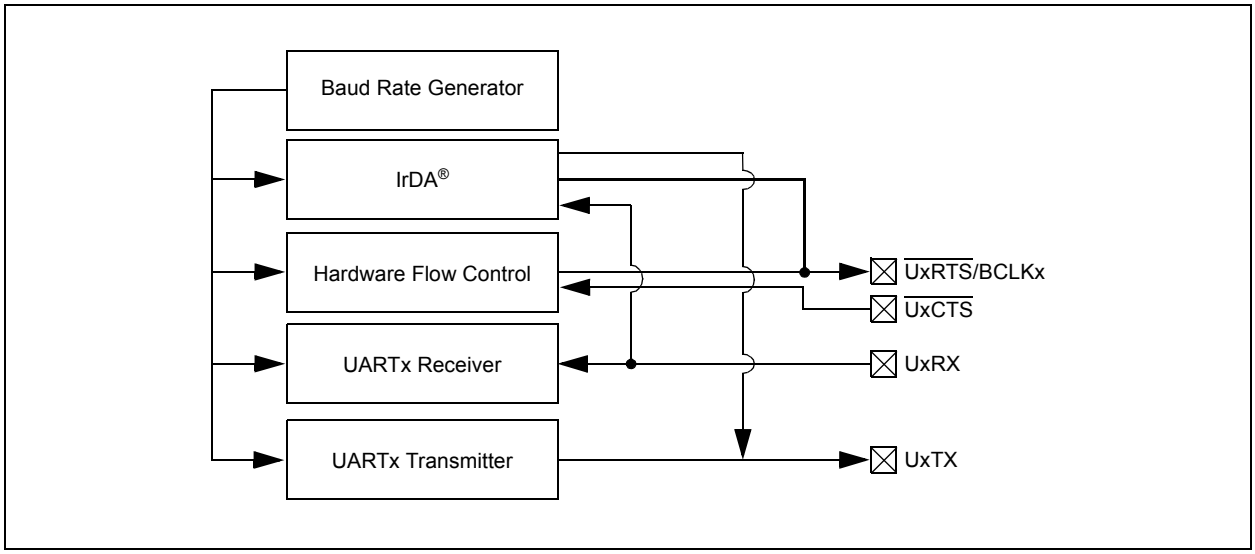
The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33EVXXXGM00X/10X device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins, and also includes an IrDA® encoder and decoder.

Note: Hardware flow control using $\overline{\text{UxRTS}}$ and $\overline{\text{UxCTS}}$ is not available on all pin count devices. See the **"Pin Diagrams"** section for availability.

The primary features of the UARTx module are:

- Full-Duplex, 8 or 9-Bit Data Transmission through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop Bits
- Hardware Flow Control Option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ Pins
- Fully Integrated Baud Rate Generator with 16-Bit Prescaler
- Baud Rates Ranging from 4.375 Mbps to 67 bps at 16x mode at 70 MIPS
- Baud Rates Ranging from 17.5 Mbps to 267 bps at 4x mode at 70 MIPS
- 4-Deep First-In First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-Bit mode with Address Detect (9^{th} bit = 1)
- Transmit and Receive Interrupts
- A Separate Interrupt for All UART Error Conditions

FIGURE 21-1: UARTx SIMPLIFIED BLOCK DIAGRAM



REGISTER 22-4: CxFCTRL: CANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FSA5	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

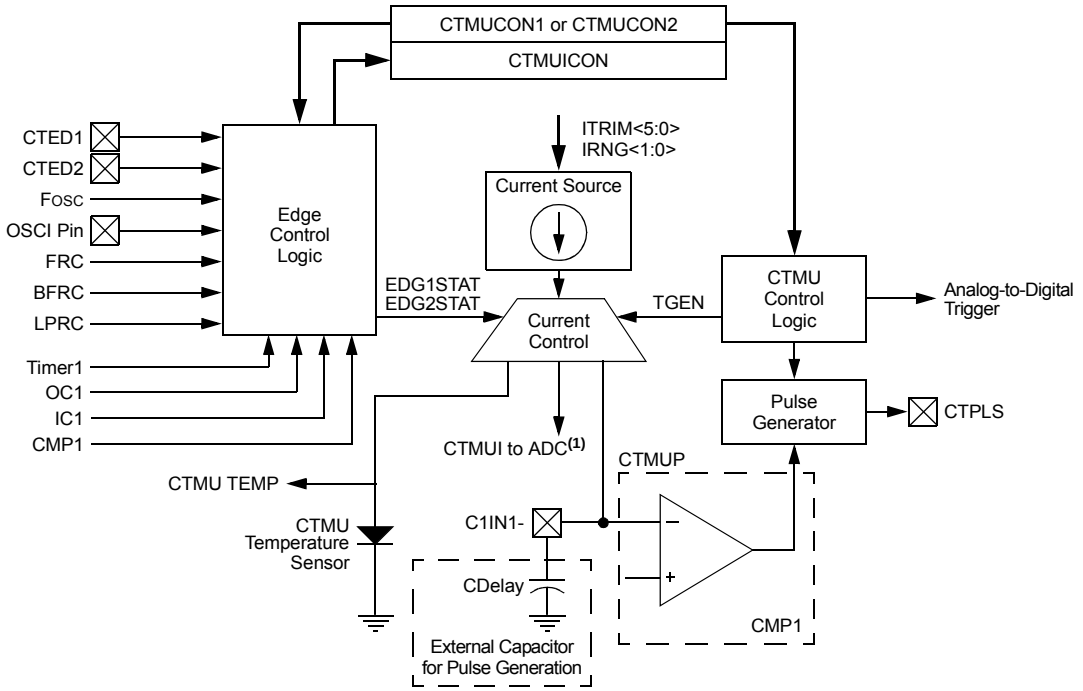
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

bit 12-6 **Unimplemented:** Read as '0'

bit 5-0 **FSA<5:0>:** FIFO Area Starts with Buffer bits
11111 = Receive Buffer RB31
11110 = Receive Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

FIGURE 23-1: CTMU BLOCK DIAGRAM



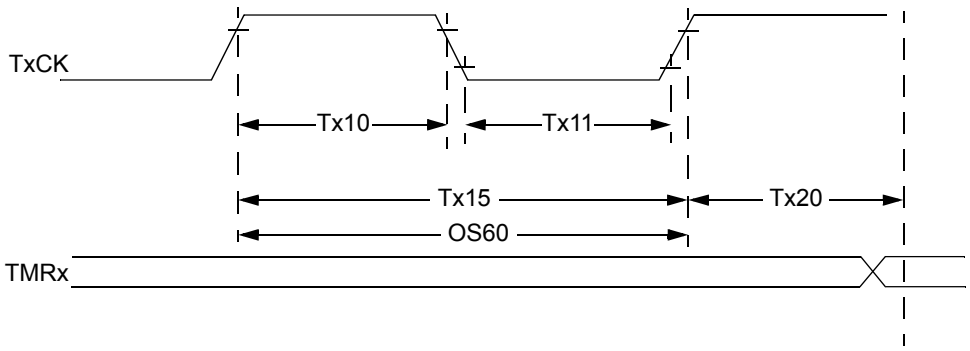
Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI to ADC	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

Note 1: Current source to particular ANx pins is provided only when 10-Bit ADC mode is chosen.

TABLE 27-2: dsPIC33EVXXXGM00X/10X CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	Description
OSCIOFNC	FOSC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is the general purpose digital I/O pin
IOL1WAY	FOSC	Peripheral Pin Select Configuration bit 1 = Allows only one reconfiguration 0 = Allows multiple reconfigurations
FCKSM<1:0>	FOSC	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
PLLKEN	FOSC	PLL Lock Wait Enable bit 1 = Clock switches to the PLL source; will wait until the PLL lock signal is valid 0 = Clock switch will not wait for PLL lock
WDTPS<3:0>	FWDT	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
WDTPRE	FWDT	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
FWDTEN<1:0>	FWDT	Watchdog Timer Enable bits 11 = WDT is enabled in hardware 10 = WDT is controlled through the SWDTEN bit 01 = WDT is enabled only while device is active and disabled in Sleep; the SWDTEN bit is disabled 00 = WDT and the SWDTEN bit are disabled
WINDIS	FWDT	Watchdog Timer Window Enable bit 1 = Watchdog Timer is in Non-Window mode 0 = Watchdog Timer is in Window mode
WDTWIN<1:0>	FWDT	Watchdog Timer Window Select bits 11 = WDT window is 25% of WDT period 10 = WDT window is 37.5% of WDT period 01 = WDT window is 50% of WDT period 00 = WDT window is 75% of WDT period
BOREN	FPOR	Brown-out Reset (BOR) Detection Enable bit 1 = BOR is enabled 0 = BOR is disabled
ICS<1:0>	FICD	ICD Communication Channel Select bits 11 = Communicates on PGEC1 and PGED1 10 = Communicates on PGEC2 and PGED2 01 = Communicates on PGEC3 and PGED3 00 = Reserved, do not use
DMTIVT<15:0>	FDMTINTVL	Lower 16 Bits of 32-Bit Field that Configures the DMT Window Interval bits
DMTIVT<31:16>	FDMTINTVH	Upper 16 Bits of 32-Bit Field that Configures the DMT Window Interval bits
DMTCNT<15:0>	FDMTCNTL	Lower 16 Bits of 32-Bit Field that Configures the DMT Instruction Count Time-out Value bits

FIGURE 30-6: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

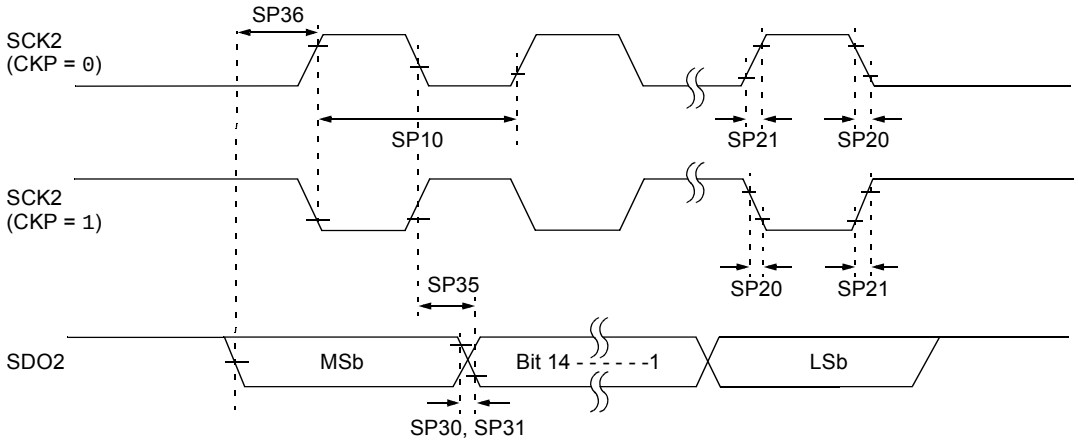
TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS (T1CON<1>) bit)		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized but not tested in manufacturing.

FIGURE 30-13: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-31: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	

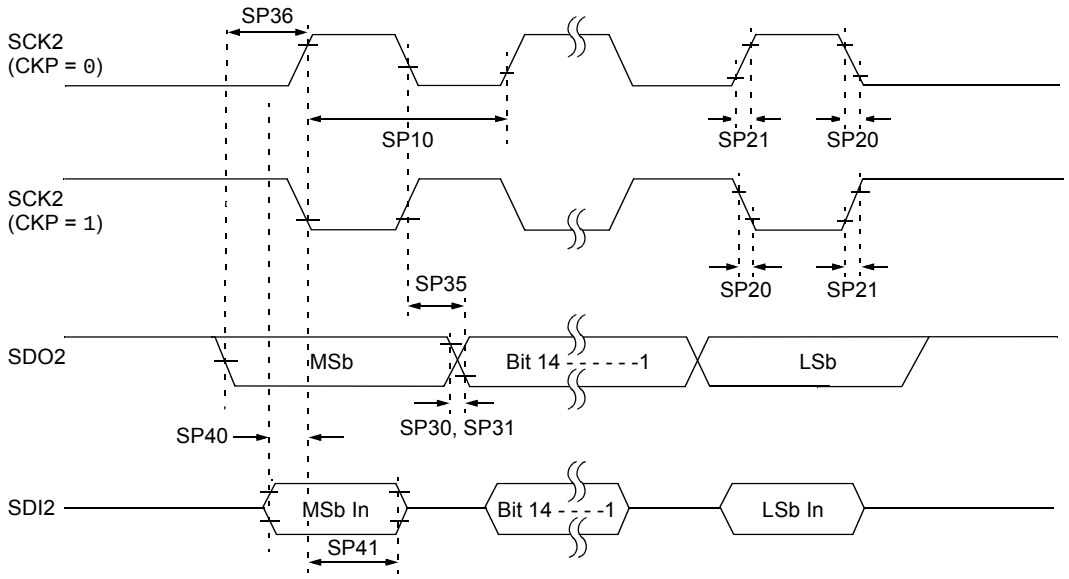
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-14: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-32: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	9	MHz	See **Note 3**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

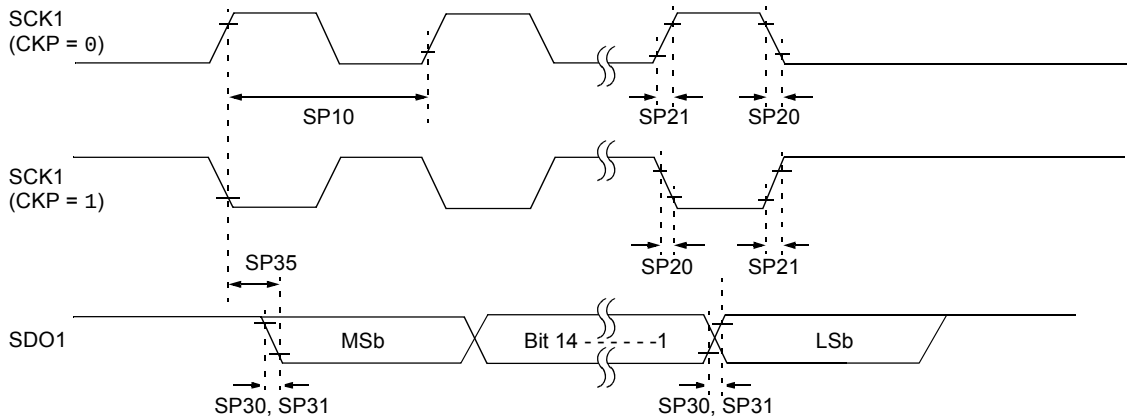
3: The minimum clock period for SCK2 is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-38: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
25 MHz	Table 30-39	—	—	0,1	0,1	0,1
25 MHz	—	Table 30-40	—	1	0,1	1
25 MHz	—	Table 30-41	—	0	0,1	1
25 MHz	—	—	Table 30-42	1	0	0
25 MHz	—	—	Table 30-43	1	1	0
25 MHz	—	—	Table 30-44	0	1	0
25 MHz	—	—	Table 30-45	0	0	0

FIGURE 30-20: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

FIGURE 32-11: TYPICAL IIDLE vs. VDD (EC MODE, 60 MIPS)

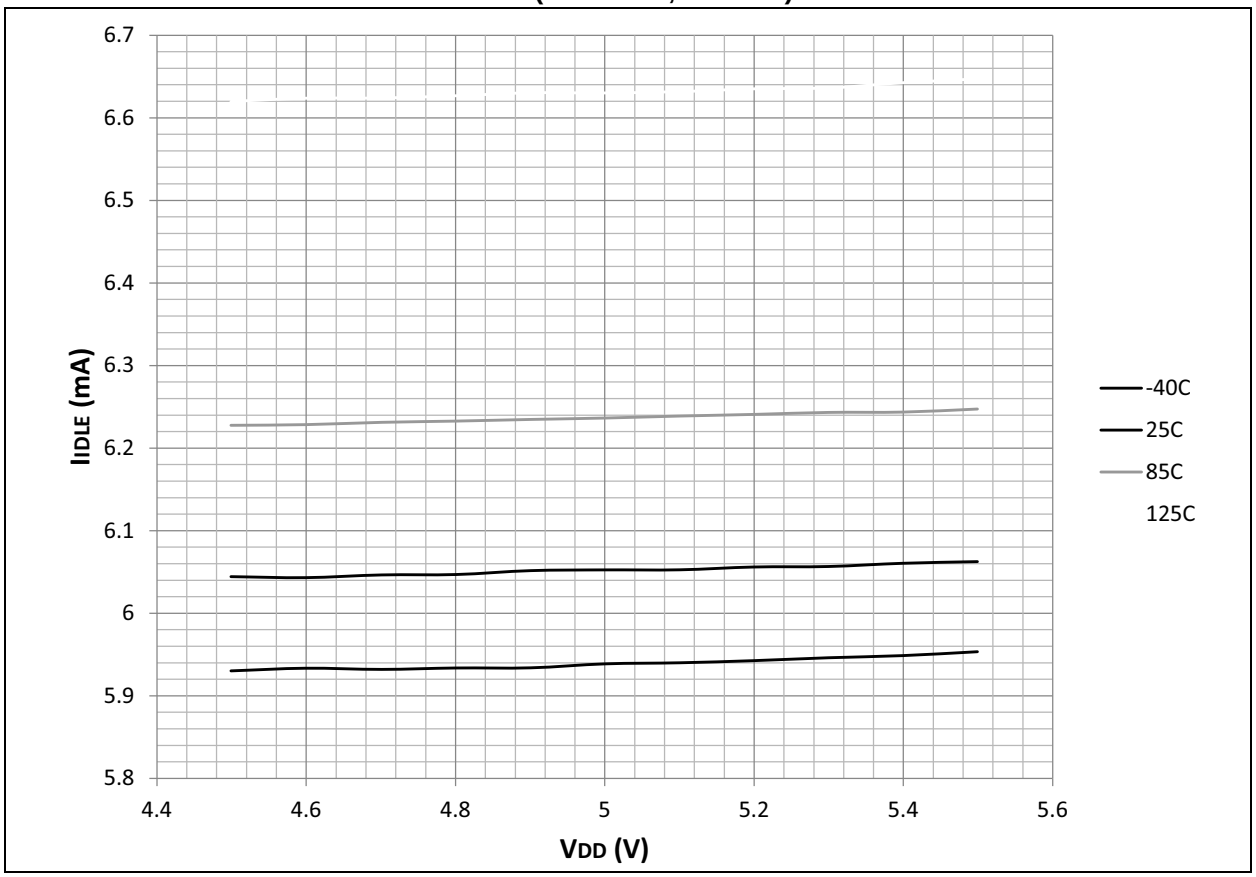
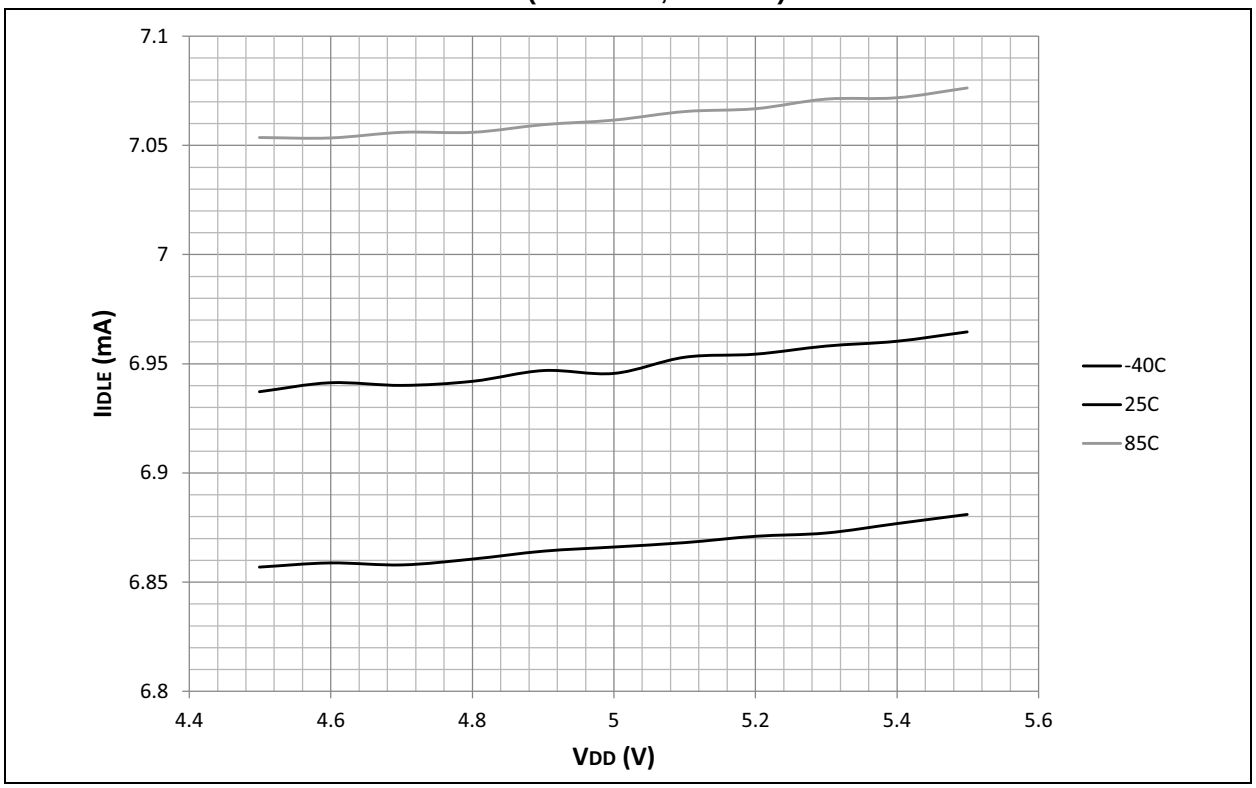


FIGURE 32-12: TYPICAL IIDLE vs. VDD (EC MODE, 70 MIPS)



32.19 ADC Gain Offset Error

FIGURE 32-49: TYPICAL ADC GAIN ERROR vs. TEMPERATURE

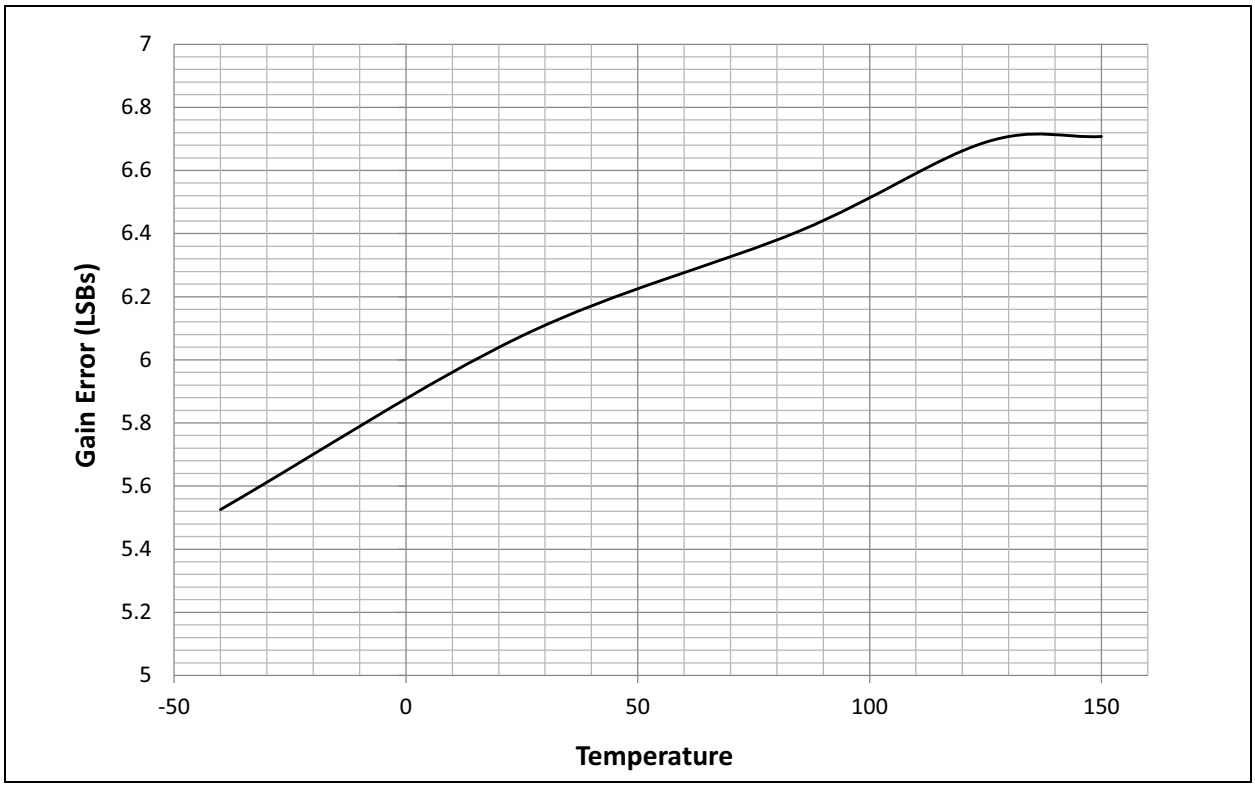


FIGURE 32-50: TYPICAL ADC OFFSET ERROR vs. TEMPERATURE

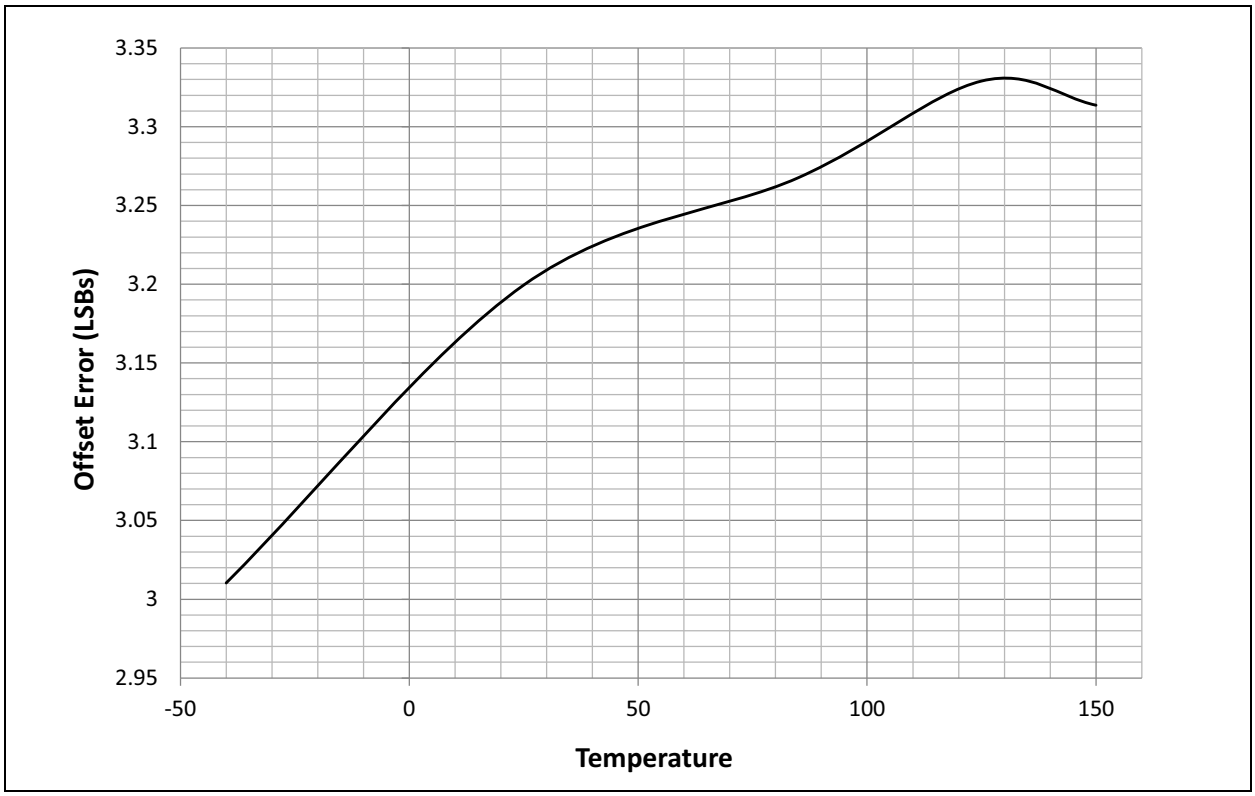
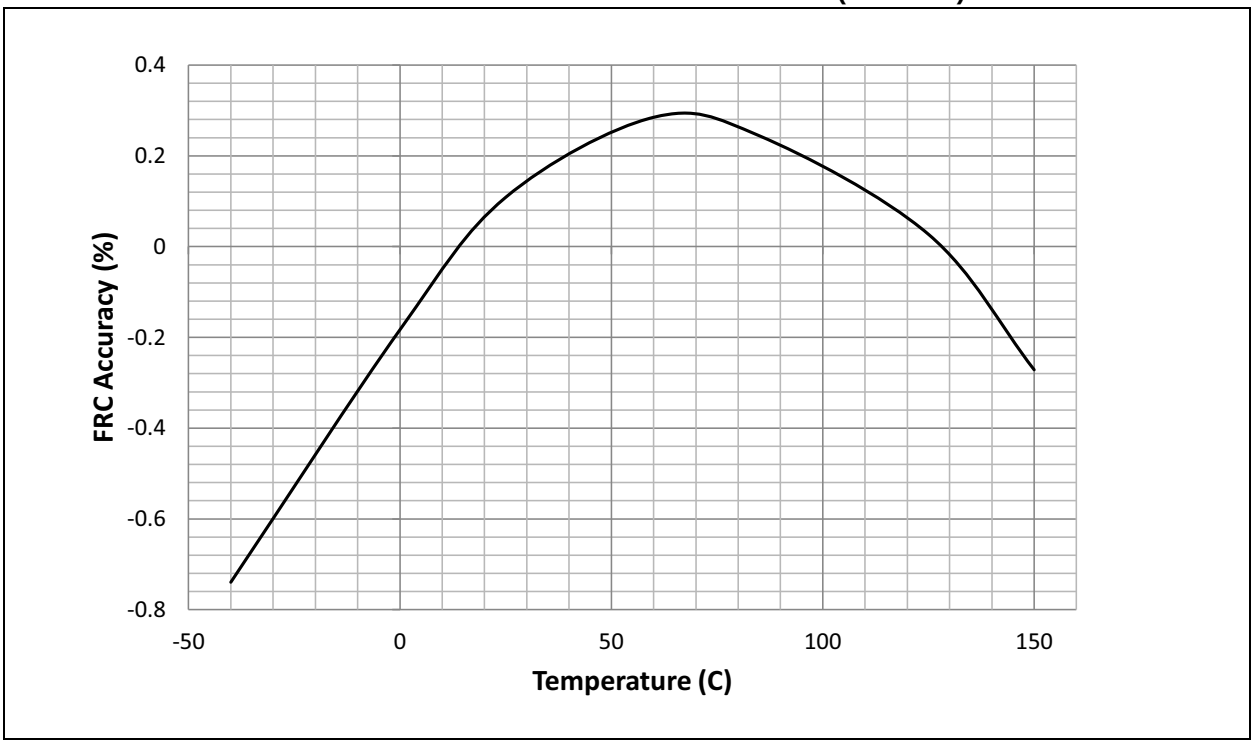


FIGURE 33-17: TYPICAL FRC ACCURACY vs. TEMPERATURE (5.5V VDD)



33.6 LPRC

FIGURE 33-18: TYPICAL LPRC ACCURACY vs. VDD

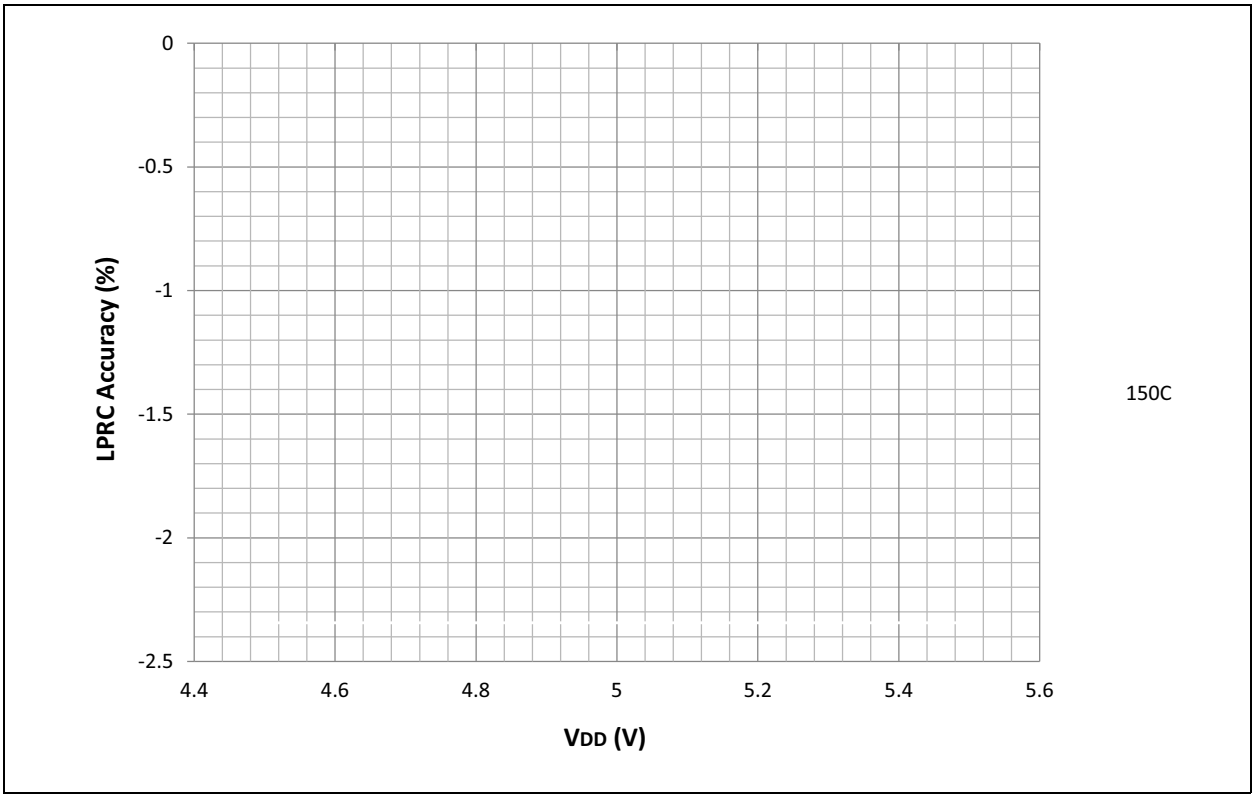


FIGURE 33-27: TYPICAL V_{OH} 4x DRIVER PINS vs. I_{OH} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)

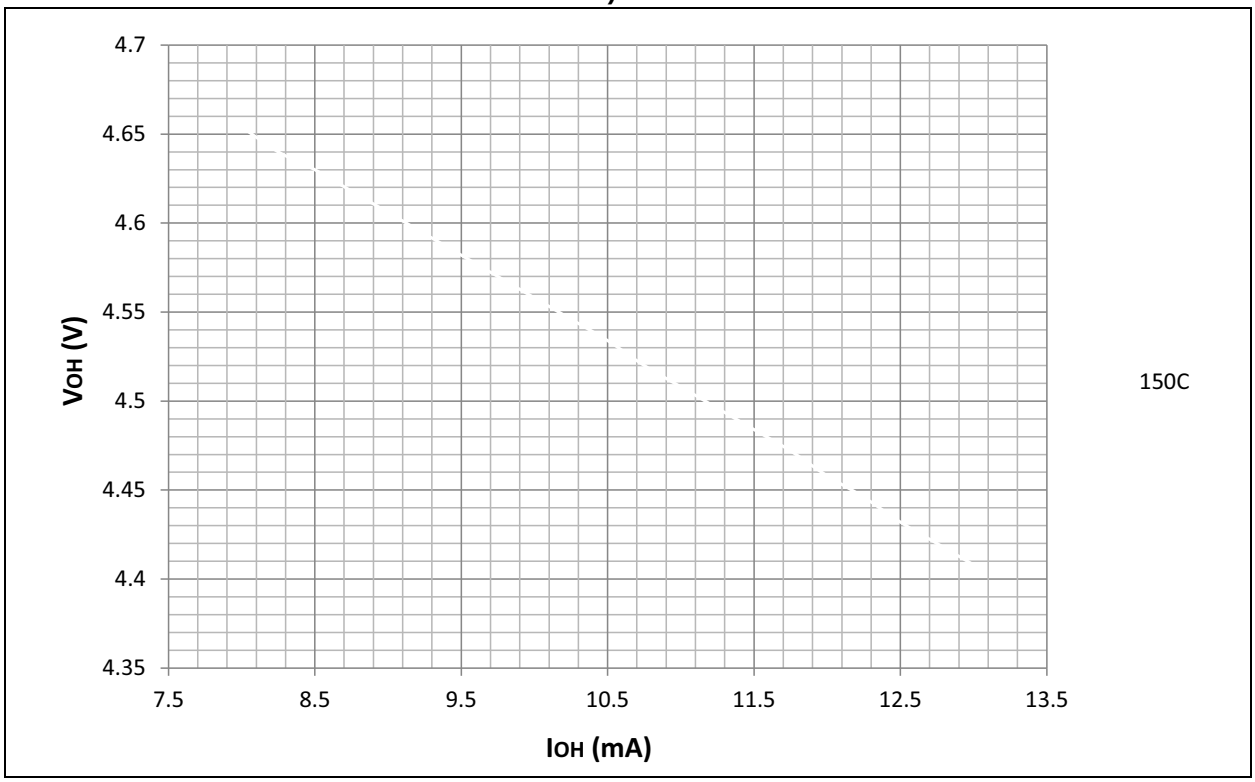
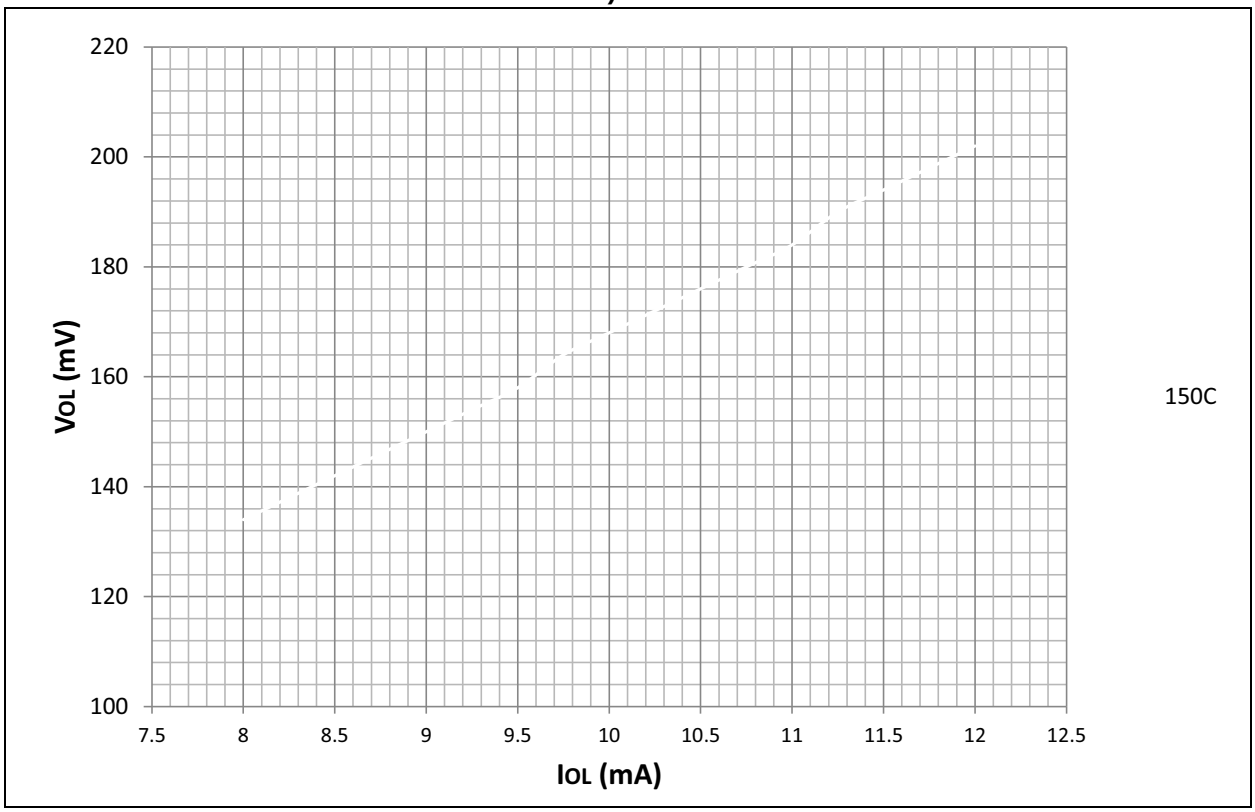


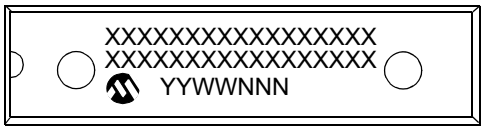
FIGURE 33-28: TYPICAL V_{OL} 8x DRIVER PINS vs. I_{OL} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



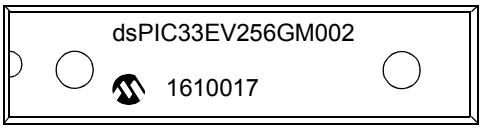
34.0 PACKAGING INFORMATION

34.1 Package Marking Information

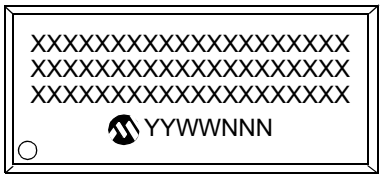
28-Lead SPDIP (.300”)



Example



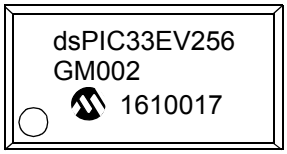
28-Lead SOIC (.300”)



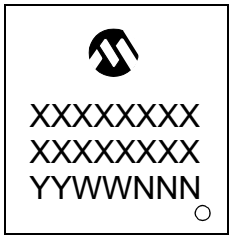
Example

28-Lead SSOP

Example



28-Lead QFN-S (6x6x0.9 mm)



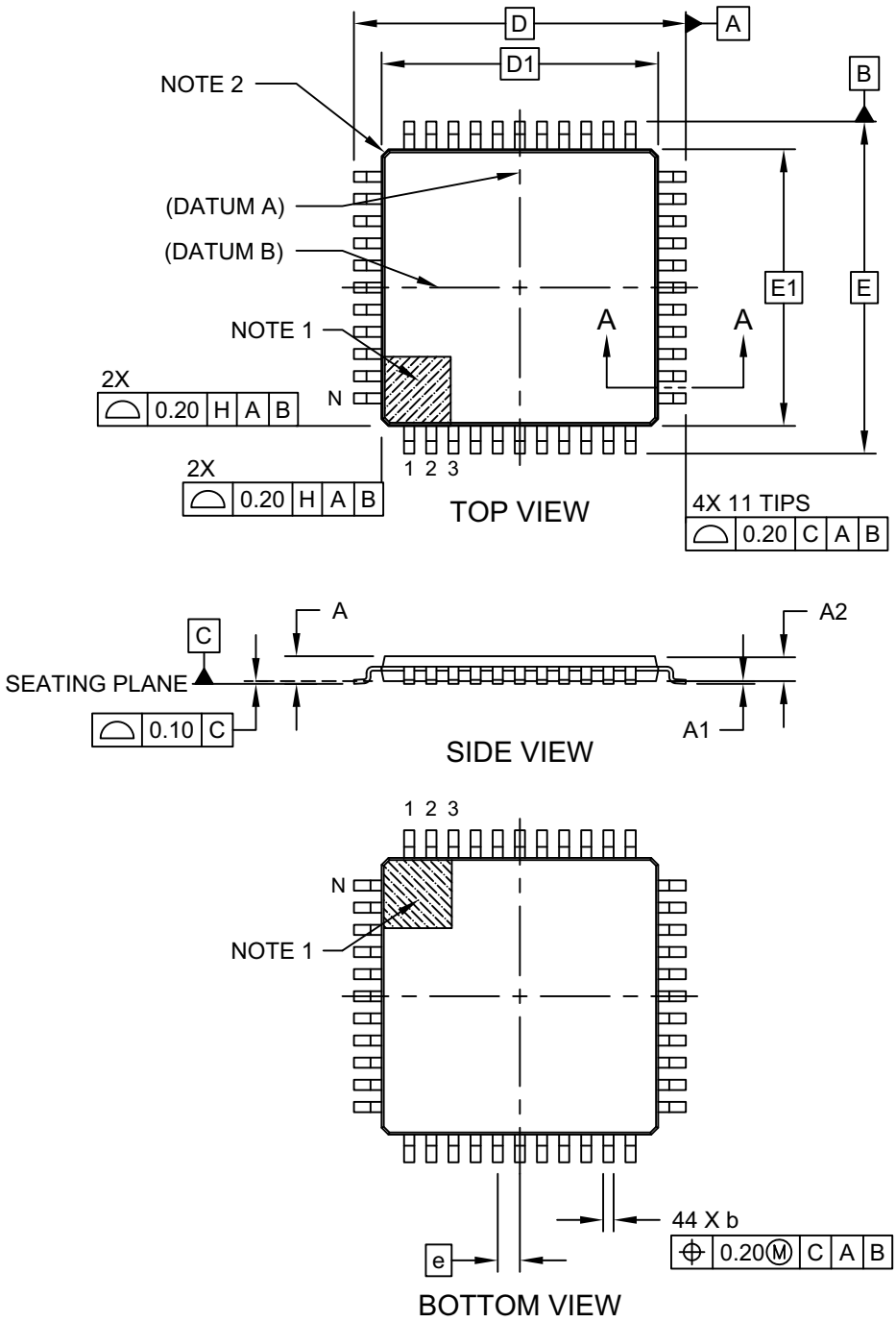
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-076C Sheet 1 of 2